

**Harmonized system of
quality assessment for
electronic
components —
Semiconductor
devices —
Integrated circuits —
Blank detail
specification for film
integrated circuits and
hybrid film integrated
circuits on the basis of
the capability approval
procedures**

ICS 31.200

This British Standard, having been prepared under the direction of the Electrotechnical Sector Board, was published under the authority of the Standards Board and comes into effect on 15 August 1997

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Amendments issued since publication

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National foreword

This British Standard reproduces verbatim IEC 60748-22-1:1997 and implements it as the UK national standard. It supersedes BS QC 760201:1992 which is withdrawn. This standard is a harmonized specification within the IEC system of quality assessment for electronic components (IECQ).

The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors, to Subcommittee EPL/47/1, Film and hybrid integrated circuits, which has the responsibility to:

- aid enquirers to understand the text;
- present to the responsible international/European committee any enquiries on the interpretation, or proposals for change, and keep the UK interests informed;
- monitor related international and European developments and promulgate them in the UK.

A list of organizations represented on this subcommittee can be obtained on request to its secretary.

The standard is to be used in conjunction with BS QC 760000 and BS QC 760200.

The British Standard which implements the IECQ Rules of Procedure is BS 9000 *General Requirements for a system for electronic components of assessed quality — Part 3:1996 Specification for the national implementation of the IECQ system*.

From 1 January 1997, all IEC publications have the number 60000 added to the old number. For instance, IEC 27-1 has been renumbered as IEC 60027-1. For a period of time during the change over from one numbering system to the other, publications may contain identifiers from both systems.

Cross-references

The British Standards which implement international or European publications referred to in this document may be found in the BSI Standards Catalogue under the section entitled “International Standards Correspondence Index”, or by using the “Find” facility of the BSI Standards Electronic Catalogue.

A British Standard does not purport to include all the necessary provisions of a contract. Users of British Standards are responsible for their correct application.

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Summary of pages

This document comprises a front cover, an inside front cover, pages i and ii, the CEI IEC title page, page ii, pages 1 to 12 and a back cover.

This standard has been updated (see copyright date) and may have had amendments incorporated. This will be indicated in the amendment table on the inside front cover.

**NORME
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INTERNATIONAL
STANDARD**

**CEI
IEC**

60748-22-1

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**Dispositifs à semiconducteurs –
Circuits intégrés –**

**Partie 22-1:
Spécification particulière cadre pour
les circuits intégrés à couches et les circuits
intégrés hybrides à couches sur la base
des procédures d'agrément de savoir-faire**

**Semiconductor devices –
Integrated circuits –**

**Part 22-1:
Blank detail specification for film
integrated circuits and hybrid film integrated circuits
on the basis of the capability approval procedures**



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